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a thermal fuse provided on the other surface of said circuit board to enter said through opening, responding to temperature of said electronic component via a heat-conducting insulating member filling said through opening for breaking said predetermined circuit; and

a through hole provided in said circuit board, wherein said thermal fuse is electrically connected to said predetermined circuit via said through hole.

A marked-up copy of the amended claim is attached as required under 37 C.F.R. § 1.121.

REMARKS

The following Remarks are a full and complete response to the Office Action dated August 29, 2002. Claims 1, 2, 4 are pending in this application, with claim 3 canceled by the present Amendment. In the outstanding Office Action, claims 1-4 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Applicant's Admitted Prior Art in view of Shirakawa et al. (GB/2,302,451). In making this rejection, the Office Action asserts that the combination of these two references teaches and/or suggests each and every element of the claimed invention. The Office Action also asserts that the combination of these two references would be obvious to one of ordinary skill in the art. Applicant respectfully disagrees.

Claim 1, as amended, recites a mount structure for a thermal fuse on a circuit board. This structure includes a circuit board having one surface where a predetermined circuit is formed. A through opening is provided in the circuit board. An electronic component is attached to the one surface of the circuit board to extend